In the specification:

Please replace the title at page 1, line 1 with the following:

Method of Manufacturing a Circuit Device with Trenches in a Conductive Foil.

Please amend the paragraph beginning at page 11, line 4 as follows:

As shown in Fig. 2 to Fig. 4, the first step of the present invention ~~resides in that~~ involves preparing a conductive foil 60 ~~is prepared and conductive patterns 51 are formed by forming~~ and isolation trenches 61 are formed in the conductive foil 60 to produce conductive patterns 51.~~, that~~ The isolation trenches 61 are shallower than a thickness of the conductive foil 60.~~, on the conductive foil 60 in regions except t~~ The conductive patterns 51 ~~on which~~ have at least a number of mounting portions for mounting circuit elements, such as circuit elements 52A and 52B as seen in Fig. 6~~ 52 are formed~~.

Please amend the paragraph beginning at page 17, line 4 as follows:

As shown in Figs. 7A, in the fourth step of the present invention, the insulating resin 50 is commonly molded to cover collectively the circuit elements 52 ~~on respective mounting portions 63~~ and to fill the isolation trenches 61.

Please amend the paragraph beginning at page 17, line 22 as follows:

In addition, in executing the transfer mold or the injection mold in the present step, as shown in Fig. 7B, each block contains mounting portions ~~63~~(reference 65 in Fig. 9) in one common mold, and the molding is executed commonly by the insulating resin 50 for every block. Therefore, an amount of resin can be reduced considerably ~~rather that the method like~~compared to the conventional transfer mold ~~by~~ which requires molding individual ~~respective~~ mounting portions ~~are molded individually~~.

Please amend the paragraph beginning at page 20, line 14 as follows:

As shown in Fig. 9, in the sixth step of the present invention, ~~the test of~~ the quality of the circuit elements 52 on respective mounting portions ~~63~~65, that are molded collectively by the insulating resin 50, is ~~carried out~~tested.

Please amend the paragraph beginning at page 20, line 25 as follows:

As shown in Fig. 9, the back surfaces of the conductive patterns 51 are exposed from the back surfaces of respective blocks 62 and respective mounting portions 65 are aligned in ~~the~~ perfectly same matrix fashion as that in forming the conductive patterns 51. Then, the characteristic parameters of the circuit elements, such as circuit elements 52A and 52B in Fig. 8, on respective mounting portions 65 ~~, etc.~~ are tested individually by bringing a probe 68 into contact with the back-surface electrodes, such as electrodes 56A, 56B, and 56C shown in Fig. 8, exposed from the insulating resin 50 of the conductive patterns 51~~, so that the decision of~~to determine the quality of the circuit elements ~~52 is made~~. Then, ~~the marking by the magnetic ink, or the like is applied to the~~ defective products are marked, for example, by magnetic ink.